MA2SD19

Silicon epitaxial planar type

For super high speed switching

■ Features

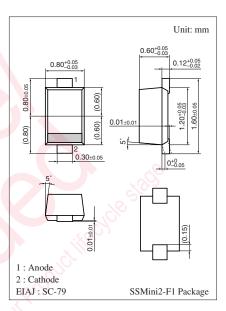
• Forward current (Average) $I_{F(AV)} = 200 \text{ mA}$ rectification is possible

• Low forward voltage: $V_F < 0.47 \ V$ • Small reverse current: $I_R < 20 \ \mu A$

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	20	V
Repetitive peak reverse voltage	V _{RRM}	20	V
Non-repetitive peak forward surge current *	I _{FSM}	1	A
Peak forward current	I_{FM}	300	mA
Forward current (Average)	$I_{F(AV)}$	200	mA
Junction temperature	T_{j}	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

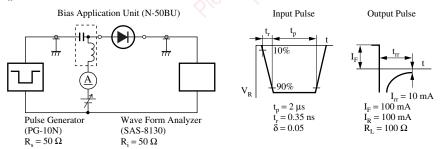


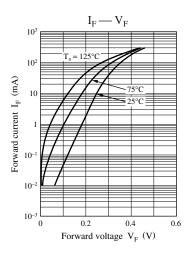
Marking Symbol: 3L

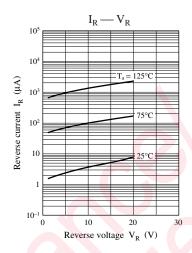
■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

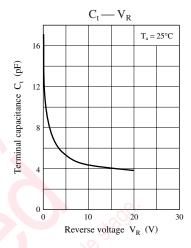
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V_F	$I_F = 200 \text{ mA}$	00		0.47	V
Reverse current	I_R	$V_R = 10 \text{ V}$		3 .	15	μΑ
Terminal capacitance	C_{t}	$V_R = 0 V, f = 1 MHz$	1.90	15		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$		2		ns
		$I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$				

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
 - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
 - 3. Absolute frequency of input and output is 250 MHz.
 - 4. *: t_{rr} measurement circuit









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